

**Amendments to the Specification:**

- (1) Please amend the title as follows:

**HIGH EFFICIENCY MICROLENS ARRAY HAVING GAP-FILLING LAYER**

- (2) Please replace paragraph [0010] with the following amended paragraph:

[0010] Referring to Fig. 1, illustrated is a sectional view of one embodiment of a microlens array 100 constructed according to aspects of the present disclosure. As evident in the description that follows, Fig. 3 also depicts aspects of at least one embodiment of a method of manufacturing the microlens array 100, such as according to one or more of the steps described below. The microlens array includes, or may include, a substrate 110 having photo sensors 120 formed therein, a passivation layer 130, and a dielectric layer 140 having microlenses 150 formed therein, thereon, and/or therefrom. The microlens array 100 also includes a dielectric film 160, and possibly a color filter 170 and a protective layer 180.

- (3) Please replace paragraph [0021] with the following amended paragraph:

[0021] Referring to Fig. 2, illustrated is a sectional view of another embodiment of the microlens array 100 shown in Fig. 1, herein designated by the reference numeral 200. As evident in the description that follows, Fig. 3 also depicts one or more aspects of at least one embodiment of a method of manufacturing the microlens array 200, such as according to one or more of the steps described below or elsewhere herein. The microlens array 200 includes, or may include, the substrate 110, the photo sensors 120, the passivation layer 130, the dielectric film 160, the color filter 170, and the protective layer 180, as described above with reference to Fig. 1. The microlens array 200 also includes a dielectric layer 210 which may be substantially similar in composition and manufacture to the dielectric layer 140 shown in Fig. 1. However, the dielectric layer 210 does not include the microlenses 150 shown in Fig. 1. In contrast, a substantial portion of the dielectric layer 210 in addition to the gaps described above may be substantially planar, possibly the result of chemical-mechanical-polishing and/or chemical-mechanical-planarizing (collectively referred to herein as CMP).